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— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*

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(54) Title: PROCESS FOR TRANSFERRING A LAYER

(57) Abstract: This transfer process comprises the following steps: (a) providing a donor substrate (2) and a support substrate (3); (b) forming a embrittlement region (4) in the donor substrate (2); (c) forming what is called a bonding layer (5) between the first part (1) of the donor substrate (2) and the support substrate (3); and (d) assembling the donor substrate (2) to the support substrate (3), and is noteworthy in that it comprises the following step: (e) exposing, in succession, portions (40) of the embrittlement region (4) to electromagnetic irradiations (6) for an exposure time at a given power density, the exposure time being chosen depending on the thickness (E) of the bonding layer so that the support substrate (3) is thermally decoupled from the first part (1) of the donor substrate (2), the exposure time being chosen depending on the power density in order to activate kinetics that weaken the embrittlement region (4).

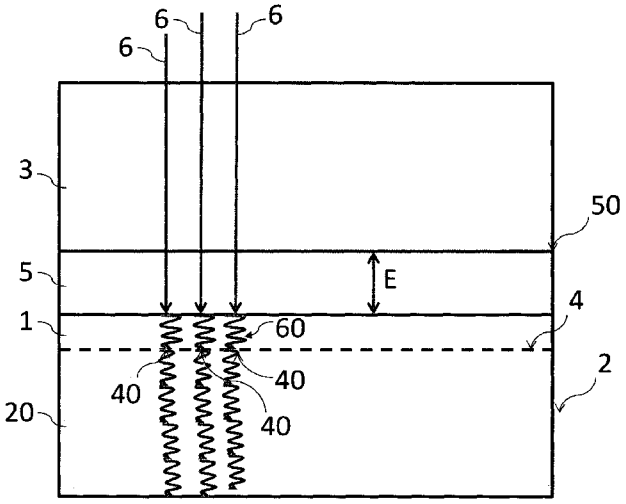


Fig 1

WO 2014/001869 A1